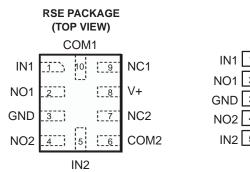


FEATURES

- Isolation in Power-Down Mode, V₊ = 0
- Specified Break-Before-Make Switching
- Low ON-State Resistance (1 Ω)
- Control Inputs Are 5.5-V Tolerant
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 1.65-V to 5.5-V Single-Supply Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)

APPLICATIONS

- Cell Phones
- PDAs
- Portable Instrumentation
- Audio and Video Signal Routing
- Low-Voltage Data-Acquisition Systems
- Communication Circuits
- Modems
- Hard Drives
- Computer Peripherals
- Wireless Terminals and Peripherals



DGS PACKAGE

(TOP VIEW)

DESCRIPTION/ORDERING INFORMATION

The TS5A23159 is a dual single-pole double-throw (SPDT) analog switch that is designed to operate from 1.65 V to 5.5 V. The device offers low ON-state resistance and excellent ON-state resistance matching with the break-before-make feature, to prevent signal distortion during the transferring of a signal from one channel to another. The device has an excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

ORDERING INFORMATION

T _A	PACKAGE	1)(2)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	VSSOP – DGS (MSOP) Tape and ree		TS5A23159DGSR	JER or JEO
-40 C 10 85 C	QFN – RSE	Tape and reel	TS5A23159RSER	JEO

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



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Configuration	Dual 2:1 Multiplexer/Demultiplexer $(2 \times SPDT)$
Number of channels	2
ON-state resistance (ron)	1.1 Ω
ON-state resistance match (Δr_{on})	0.1 Ω
ON-state resistance flatness (ron(flat))	0.15 Ω
Turn-on/turn-off time (t _{ON} /t _{OFF})	20 ns/15 ns
Break-before-make time (t _{BBM})	12 ns
Charge injection (Q _C)	–7 pC
Bandwidth (BW)	100 MHz
OFF isolation (O _{ISO})	–65 dB at 1 MHz
Crosstalk (X _{TALK})	–66 dB at 1 MHz
Total harmonic distortion (THD)	0.01%
Leakage current (I _{NO(OFF)} /I _{NC(OFF)})	±20 nA
Power-supply current (I ₊)	0.1 µA
Package options	10-pin VSSOP and QFN

SUMMARY OF CHARACTERISTICS⁽¹⁾

(1) $V_+ = 5 V, T_A = 25^{\circ}C$

FUNCTION TABLE

IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	ON	OFF
Н	OFF	ON



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Absolute Minimum and Maximum Ratings⁽¹⁾⁽²⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V+	Supply voltage range ⁽³⁾		-0.5	6.5	V
V _{NC} V _{NO} V _{COM}	Analog voltage range ⁽³⁾⁽⁴⁾⁽⁵⁾	nalog voltage range ⁽³⁾⁽⁴⁾⁽⁵⁾		V ₊ + 0.5	V
I _K	Analog port diode current	$V_{NC}, V_{NO}, V_{COM} < 0$	-50		mA
I _{NC}	On-state switch current		-200	200	
I _{NO} I _{COM}	On-state peak switch current ⁽⁶⁾	V_{NC} , V_{NO} , $V_{COM} = 0$ to V_{+}	-400	400	mA
VI	Digital input voltage range ⁽³⁾⁽⁴⁾		-0.5	6.5	V
I _{IK}	Digital input clamp current	V ₁ < 0	-50		mA
l+	Continuous current through V ₊			100	mA
I _{GND}	Continuous current through GND		-100	100	mA
•	Decline of the survey line of decree (7)	DGS package		165	0000
θ_{JA}	Package thermal impedance ⁽⁷⁾	RSE package		TBD	°C/W
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(3) All voltages are with respect to ground, unless otherwise specified.

(4) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(5) This value is limited to 5.5 V maximum.

(6) Pulse at 1-ms duration < 10% duty cycle

(7) The package thermal impedance is calculated in accordance with JESD 51-7.

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Electrical Characteristics for 5-V Supply⁽¹⁾

 V_{\star} = 4.5 V to 5.5 V, T_{A} = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	T _A	٧,	MIN	TYP	MAX	UNIT
Analog Switch	1			1					
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V ₊	V
Peak ON	r .	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$	Switch ON,	25°C	4.5 V		0.8	1.1	Ω
resistance	r _{peak}	$I_{COM} = -100 \text{ mA},$	See Figure 14	Full	4.5 V			1.5	32
ON-state	r _{on}	V_{NO} or V_{NC} = 2.5 V,	Switch ON,	25°C	4.5 V		0.7	0.9	Ω
resistance	on	$I_{COM} = -100 \text{ mA},$	See Figure 14	Full	4.0 V			1.1	32
ON-state				25°C			0.05	0.1	
resistance match between channels	Δr_{on}	V_{NO} or V_{NC} = 2.5 V, I_{COM} = -100 mA,	Switch ON, See Figure 14	Full	4.5 V			0.1	Ω
ON-state		$\begin{array}{l} 0 \leq (V_{\rm NO} \mbox{ or } V_{\rm NC}) \leq V_{+}, \\ I_{\rm COM} = -100 \mbox{ mA}, \end{array}$	Switch ON, See Figure 14	25°C			0.15		
resistance	r _{on(flat)}	$V_{NO} \text{ or } V_{NC} = 1 \text{ V}, 1.5 \text{ V},$	Switch ON,	25°C	4.5 V		0.1	0.25	Ω
flatness		2.5 V, I _{COM} = -100 mA,	See Figure 14	Full				0.25	
		V_{NC} or $V_{NO} = 1 V$,		25°C		-20	2	20	
NC, NO OFF leakage current	I _{NO(OFF)} , I _{NC(OFF)}	$\label{eq:VCOM} \begin{array}{l} V_{COM} = 1 \ V \ to \ 4.5 \ V, \\ or \\ V_{NC} \ or \ V_{NO} = 4.5 \ V, \\ V_{COM} = 1 \ V \ to \ 4.5 \ V, \end{array}$	Switch OFF, See Figure 15	Full	5.5 V	-100		100	nA
ourient	I _{NC(PWROFF)} ,	V_{NC} or $V_{NO} = 0$ to 5.5 V,	Switch OFF,	25°C	0.14	-1	0.2	1	
	I _{NO(PWROFF)}	$V_{COM} = 5.5 V \text{ to } 0,$	See Figure 15	Full	0 V	-20		20	μA
		V_{NC} or $V_{NO} = 1 V$,		25°C		-20	2	20	
NC, NO ON leakage current	I _{NO(ON)} , I _{NC(ON)}	$\label{eq:V_COM} \begin{array}{l} V_{\text{COM}} = Open,\\ or\\ V_{\text{NC}} \; or \; V_{\text{NO}} = 4.5 \; V,\\ V_{\text{COM}} = Open, \end{array}$	Switch ON, See Figure 16	Full	5.5 V	-100		100	nA
СОМ		V_{NC} or $V_{NO} = 0$ to 5.5 V,	Switch OFF,	25°C		-1	0.1	1	
OFF leakage current	I _{COM(PWROFF)}	$V_{COM} = 5.5 V \text{ to } 0,$	See Figure 15	Full	0 V	-20		20	μA
		V _{NC} or V _{NO} = Open,		25°C		-20	2	20	
COM ON leakage current	I _{COM(ON)}		Switch ON, See Figure 16	Full	5.5 V	-100		100	nA
Digital Control I	nputs (IN1, IN2) ⁽²⁾						I	
Input logic high	V _{IH}			Full		2.4		5.5	V
Input logic low	V _{IL}			Full		0		0.8	V
Input leakage current	I _{IH} , I _{IL}	V _I = 5.5 V or 0		25°C Full	5.5 V	-2 -100		2 100	nA
				Full		-100		100	

 The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
 All unused digital inputs of the device must be held at V₊ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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Electrical Characteristics for 5-V Supply (continued)

 $V_{+} = 4.5$ V to 5.5 V, $T_{A} = -40^{\circ}$ C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	TA	٧.	MIN	TYP	MAX	UNIT
Dynamic		<u>.</u>							
-		V _{COM} = V ₊ ,	C ₁ = 35 pF,	25°C	5 V 4.5 V	1	8	13	
Turn-on time	t _{ON}	$R_L = 50 \Omega,$	See Figure 18	Full	to 5.5 V	1		16.5	ns
				25°C	5 V	1	5	8	
Turn-off time	t _{OFF}	$V_{COM} = V_+,$ $R_L = 50 \ \Omega,$	C _L = 35 pF, See Figure 18	Full	4.5 V to 5.5 V	1		8	ns
				25°C	5 V	1	5.5	13	
Break-before- make time	t _{BBM}	$V_{NC} = V_{NO} = V_{+},$ $R_{L} = 50 \ \Omega,$	C _L = 35 pF, See Figure 19	Full	4.5 V to 5.5 V	1		14	ns
Charge injection	Q _C	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C _L = 1 nF, See Figure 23	25°C	5 V		-7		рС
NC, NO OFF capacitance	C _{NC(OFF)} , C _{NO(OFF)}	V_{NC} or V_{NO} = V ₊ or GND, Switch OFF,	See Figure 17	25°C	5 V		18		pF
NC, NO ON capacitance	C _{NC(ON)} , C _{NO(ON)}	V_{NC} or $V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 17	25°C	5 V		55		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 17	25°C	5 V		54.5		pF
Digital input capacitance	CI	$V_1 = V_+$ or GND,	See Figure 17	25°C	5 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 20	25°C	5 V		100		MHz
OFF isolation	O _{ISO}	$ \begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array} $	Switch OFF, See Figure 21	25°C	5 V		-64		dB
Crosstalk	X _{TALK}	$ \begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array} $	Switch ON, See Figure 22	25°C	5 V		-64		dB
Total harmonic distortion	THD	$ \begin{aligned} R_L &= 600 \ \Omega, \\ C_L &= 50 \ pF, \end{aligned} $	f = 20 Hz to 20 kHz, See Figure 24	25°C	5 V		0.004		%
Supply									
Positive			0. 11. 01. 07.	25°C			10	50	
supply current	I+	$V_1 = V_+$ or GND,	Switch ON or OFF	Full	5.5 V			750	nA

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Electrical Characteristics for 3.3-V Supply⁽¹⁾

 V_{\star} = 3 V to 3.6 V, T_{A} = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	T _A	۷.	MIN	TYP	MAX	UNIT
Analog Switch				•					
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V+	V
Peak ON resistance	r _{peak}	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 14	25°C Full	3 V		1.3	1.6 2	Ω
ON-state resistance	r _{on}	V_{NO} or V_{NC} = 2 V, I_{COM} = -100 mA,	Switch ON, See Figure 14	25°C Full	3 V		1.2	1.5 1.7	Ω
ON-state				25°C			0.1	0.15	
resistance match between channels	Δr _{on}	V_{NO} or V_{NC} = 2 V, 0.8 V, I_{COM} = -100 mA,	Switch ON, See Figure 14	Full	3 V		0.2	0.1.0	Ω
ON-state		$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 14	25°C			0.15		
resistance flatness	r _{on(flat)}	$V_{\rm NO} \text{ or } V_{\rm NC} = 2 \text{ V}, 0.8 \text{ V},$	Switch ON,	25°C	3 V				Ω
namess		$I_{COM} = -100 \text{ mA},$	See Figure 14	Full					
		V_{NC} or $V_{NO} = 1 V$,		25°C		-20	2	20	
NC, NO OFF leakage current	I _{NO(OFF)} , I _{NC(OFF)}		Switch OFF, See Figure 15	Full	3.6 V	-50		50	nA
content	I _{NC(PWROFF)} ,	V_{NC} or $V_{NO} = 0$ to 3.6 V,	Switch OFF,	25°C	<u> </u>	-1	0.2	1	
	I _{NO(PWROFF)}	$V_{COM} = 3.6 V \text{ to } 0,$	See Figure 15	Full	0 V	-15		15	μA
		V_{NC} or $V_{NO} = 1 V$,		25°C		-10	2	10	
NC, NO ON leakage current	I _{NO(ON)} , I _{NC(ON)}		Switch ON, See Figure 16	Full	3.6 V	-20		20	nA
COM		V_{NC} or $V_{NO} = 3.6$ V to 0,	Switch OFF,	25°C		-1	0.2	1	
OFF leakage current	I _{COM} (PWROFF)	$V_{\rm COM} = 0$ to 3.6 V,	See Figure 15	Full	0 V	-15		15	μA
		V_{NC} or V_{NO} = Open,		25°C		-10	2	10	
COM ON leakage current	I _{COM(ON)}		Switch ON, See Figure 16	Full	3.6 V	-20		20	nA
Digital Control In	puts (IN1, IN2) ⁽²⁾			•					
Input logic high	V _{IH}			Full		2		5.5	V
Input logic low	V _{IL}			Full		0		0.8	V
Input leakage	I _{IH} , I _{IL}	V ₁ = 5.5 V or 0		25°C	3.6 V	-2		2	nA
current				Full		-20		20	

 The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
 All unused digital inputs of the device must be held at V₊ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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Electrical Characteristics for 3.3-V Supply (continued)

 V_{+} = 3 V to 3.6 V, T_{A} = $-40^{\circ}C$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	TA	۷,	MIN	TYP	MAX	UNIT
Dynamic		1		r		1			
			0 25 55	25°C	3.3 V	5	11	19	
Turn-on time	t _{ON}	$V_{COM} = V_{+},$ R _L = 50 Ω,	C _L = 35 pF, See Figure 18	Full	3 V to 3.6 V	3		22	ns
			0 25 55	25°C	3.3 V	1	5	9	
Turn-off time	t _{OFF}		C _L = 35 pF, See Figure 18	Full	3 V to 3.6 V	1		9	ns
Break-before-			0 25 55	25°C	3.3 V	1	7	17	
make time	t _{BBM}		C _L = 35 pF, See Figure 19	Full	3 V to 3.6 V	1		20	ns
Charge injection	Q _C		C _L = 1 nF, See Figure 23	25°C	3.3 V		-4		рС
NC, NO OFF capacitance	C _{NC(OFF)} , C _{NO(OFF)}	V_{NC} or $V_{NO} = V_+$ or GND, Switch OFF,	See Figure 17	25°C	3.3 V		18		pF
NC, NO ON capacitance	C _{NC(ON)} , C _{NO(ON)}	V_{NC} or $V_{NO} = V_+$ or GND, Switch ON,	See Figure 17	25°C	3.3 V		56		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 17	25°C	3.3 V		56		pF
Digital input capacitance	CI	$V_1 = V_+ \text{ or GND},$	See Figure 17	25°C	3.3 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 20	25°C	3.3 V		100		MHz
OFF isolation	O _{ISO}	$\begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array}$	Switch OFF, See Figure 21	25°C	3.3 V		-64		dB
Crosstalk	X _{TALK}	$ \begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array} $	Switch ON, See Figure 22	25°C	3.3 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	3.3 V		0.01		%
Supply									
Positive supply current	l ₊	$V_1 = V_+$ or GND,	Switch ON or OFF	25°C Full	3.6 V			25 150	nA

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Electrical Characteristics for 2.5-V Supply⁽¹⁾

 $V_{+} = 2.3 \text{ V}$ to 2.7 V, $T_{A} = -40^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST COND	ITIONS	TA	V.	MIN	TYP	MAX	UNIT
Analog Switch	1			I	ı			I	
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V+	V
Peak ON resistance	r _{peak}	$ \begin{array}{l} 0 \leq (V_{NO} \text{ or } V_{NC}) \leq V_{+}, \\ I_{COM} = -8 \text{ mA}, \end{array} $	Switch ON, See Figure 14	25°C Full	2.3 V		1.8	2.5 2.7	Ω
ON-state resistance	r _{on}	V_{NO} or V_{NC} = 1.8 V, I_{COM} = -8 mA,	Switch ON, See Figure 14	25°C Full	2.3 V		1.5	2 2.4	Ω
ON-state				25°C			0.15	0.2	
resistance match between channels	Δr _{on}	V_{NO} or V_{NC} = 1.8 V, 0.8 V, I_{COM} = -8 mA,	Switch ON, See Figure 14	Full	2.3 V			0.2	Ω
ON-state		$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -8 \text{ mA},$	Switch ON, See Figure 14	25°C			0.6		
resistance flatness	r _{on(flat)}	$V_{\rm NO} \text{ or } V_{\rm NC} = 0.8 \text{ V}, 1.8 \text{ V},$	Switch ON,	25°C	2.3 V		0.6	1	Ω
naticss		$I_{COM} = -8 \text{ mA},$	See Figure 14	Full				1	
		V_{NC} or $V_{NO} = 0.5 V$,		25°C		-20	2	20	
NC, NO OFF leakage current	I _{NO(OFF)} , I _{NC(OFF)}		Switch OFF, See Figure 15	Full	2.3 V	-50		50	nA
content	I _{NC(PWROFF)} ,	V_{NC} or $V_{NO} = 0$ to 2.7 V,	Switch OFF,	25°C	<u> </u>	-1	0.1	1.0	
	I _{NO(PWROFF)}	$V_{COM} = 2.7 V \text{ to } 0,$	See Figure 15	Full	0 V	-10		10	μA
		V_{NC} or $V_{NO} = 0.5 V$,		25°C		-10	2	10	
NC, NO ON leakage current	I _{NO(ON)} , I _{NC(ON)}		Switch ON, See Figure 16	Full	2.7 V	-20		20	nA
COM		V_{NC} or $V_{NO} = 2.7$ V to 0,	Switch OFF,	25°C		-1	0.1	1	
OFF leakage current	ICOM(PWROFF)	$V_{COM} = 0$ to 2.7 V,	See Figure 15	Full	0 V	-10		10	μA
		V _{NC} or V _{NO} = Open,		25°C		-10	2	10	
COM ON leakage current	I _{COM(ON)}	$\label{eq:VCOM} \begin{array}{l} V_{COM} = 0.5 \ \text{V}, \\ \text{or} \\ V_{NC} \ \text{or} \ \text{V}_{NO} = \text{Open}, \\ V_{COM} = 2.2 \ \text{V}, \end{array}$	Switch ON, See Figure 16	Full	2.7 V	-20		20	nA
Digital Control In	puts (IN1, IN2) ⁽²⁾)			1	1			
Input logic high	V _{IH}			Full		1.8		5.5	V
Input logic low	V _{IL}			Full		0		0.6	V
Input leakage	Luc I	V ₁ = 5.5 V or 0		25°C	2.7 V	-2		2	nA
current	$I_{\rm IH}, I_{\rm IL}$	$v_{\rm I} = 0.0 \ v_{\rm OI} \ 0$		Full	2.1 V	-20		20	ПА

 The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
 All unused digital inputs of the device must be held at V₊ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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Electrical Characteristics for 2.5-V Supply⁽¹⁾ (Continued)

 $V_{+} = 2.3 \text{ V}$ to 2.7 V, $T_{A} = -40^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	TA	V.	MIN	TYP	MAX	UNIT
Dynamic					4				
			0 05 5	25°C	2.5 V	5	15	28	
Turn-on time	t _{ON}	$V_{COM} = V_+, \\ R_L = 50 \ \Omega,$	C _L = 35 pF, See Figure 18	Full	2.3 V to 2.7 V	5		32	ns
			0 05 -5	25°C	2.5 V	2	6	9	
Turn-off time	t _{OFF}	$V_{COM} = V_+, \\ R_L = 50 \ \Omega,$	C _L = 35 pF, See Figure 18	Full	2.3 V to 2.7 V	2		10	ns
Dan al hafana			0 05 5	25°C	2.5 V	1	10	27	
Break-before- make time	t _{BBM}		C _L = 35 pF, See Figure 19	Full	2.3 V to 2.7 V	1		30	ns
Charge injection	Q _C	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C _L = 1 nF, See Figure 23	25°C	2.5 V		-3		рС
NC, NO OFF capacitance	C _{NC(OFF)} , C _{NO(OFF)}	V_{NC} or $V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 17	25°C	2.5 V		18.5		pF
NC, NO ON capacitance	C _{NC(ON)} , C _{NO(ON)}	V_{NC} or $V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 17	25°C	2.5 V		56.5		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 17	25°C	2.5 V		56.5		pF
Digital input capacitance	CI	$V_{I} = V_{+}$ or GND,	See Figure 17	25°C	2.5 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 20	25°C	2.5 V		100		MHz
OFF isolation	O _{ISO}	$ \begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array} $	Switch OFF, See Figure 21	25°C	2.5 V		-64		dB
Crosstalk	X _{TALK}	$ \begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array} $	Switch ON, See Figure 22	25°C	2.5 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	2.5 V		0.02		%
Supply	1	-			1				
Positive supply			Switch ON or OFF	25°C	271		10	25	~ ^
current	I+	$V_I = V_+ \text{ or } GND,$	Switch ON or OFF	Full	2.7 V			100	nA

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

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Electrical Characteristics for 1.8-V Supply⁽¹⁾

 V_{+} = 1.65 V to 1.95 V, T_{A} = –40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONE	DITIONS	TA	V.	MIN	TYP	MAX	UNIT
Analog Switch									
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V+	V
Peak ON	-	$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$	Switch ON,	25°C	1.65 V		5		Ω
resistance	r _{peak}	$I_{COM} = -2 \text{ mA},$	See Figure 14	Full	1.05 V			15	12
ON-state	r	V_{NO} or V_{NC} = 1.5 V,	Switch ON,	25°C	1.65 V		2	2.5	Ω
resistance	r _{on}	$I_{COM} = -2 \text{ mA},$	See Figure 14	Full	1.05 V			3.5	12
ON-state				25°C			0.15	0.4	
resistance match between channels	Δr _{on}	V_{NO} or V_{NC} = 0.6 V, 1.5 V, I _{COM} = -2 mA,	Switch ON, See Figure 14	Full	1.65 V			0.4	Ω
ON-state		$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -2 \text{ mA},$	Switch ON, See Figure 14	25°C			5		
resistance flatness	r _{on(flat)}	$V_{\rm NO} \text{ or } V_{\rm NC} = 0.6 \text{ V}, 1.5 \text{ V},$	Switch ON,	25°C	1.65 V		4.5		Ω
liatiless		$I_{COM} = -2 \text{ mA},$	See Figure 14	Full	-				
		V_{NC} or $V_{NO} = 0.3 V$,		25°C		-20	2	20	
NC, NO OFF leakage	I _{NO(OFF)} , I _{NC(OFF)}		Switch OFF, See Figure 15	Full	1.65 V	-50		50	nA
current	1	V_{NC} or $V_{NO} = 0$ to	Switch OFF,	25°C		-1	0.1	1	
	I _{NC(PWROFF)} , I _{NO(PWROFF)}	1.95 V, V _{COM} = 1.95 V to 0,	See Figure 15	Full	0 V	-5		5	μA
		$V_{\rm NC}$ or $V_{\rm NO}$ = 0.3 V,		25°C		-5	2	5	
NC, NO ON leakage current	I _{NO(ON)} , I _{NC(ON)}	$\label{eq:V_COM} \begin{array}{l} V_{COM} = Open, \\ or \\ V_{NC} \mbox{ or } V_{NO} = 1.65 \mbox{ V}, \\ V_{COM} = Open, \end{array}$	Switch ON, See Figure 16	Full	1.95 V	-20		20	nA
COM		V_{NC} or V_{NO} = 1.95 V to 0,	Switch OFF,	25°C		-1	0.1	1	
OFF leakage current	I _{COM} (PWROFF)	$V_{COM} = 0$ to 1.95 V,	See Figure 15	Full	0 V	-5		5	μA
		V _{NC} or V _{NO} = Open,		25°C		-10	2	10	
COM ON leakage current	I _{COM(ON)}	$ \begin{array}{l} V_{COM} = 0.3 \ V, \\ or \\ V_{NC} \ or \ V_{NO} = Open, \\ V_{COM} = 1.65 \ V, \end{array} $	Switch ON, See Figure 16	Full	1.95 V	-20		20	nA
Digital Control In	puts (IN1, IN2) ⁽²⁾				1				
Input logic high	V _{IH}			Full		1.5		5.5	V
Input logic low	V _{IL}			Full		0		0.6	V
Input leakage	I _{IH} , I _{IL}	V _I = 5.5 V or 0		25°C	1.95 V	-2		2	nA
current	'IH', 'IL			Full	1.55 v	-20		20	117

 The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
 All unused digital inputs of the device must be held at V₊ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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Electrical Characteristics for 1.8-V Supply⁽¹⁾ (Continued)

 V_{+} = 1.65 V to 1.95 V, T_{A} = -40°C to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CON	DITIONS	TA	V.	MIN	TYP	MAX	UNIT
Dynamic									
			0 05 5	25°C	1.8 V	10	27.5	48.5	
Turn-on time	t _{ON}	$V_{COM} = V_+, \\ R_L = 50 \ \Omega,$	C _L = 35 pF, See Figure 18	Full	1.65 V to 1.95 V	10		55	ns
			0 05 -5	25°C	1.8 V	2	6.5	11	
Turn-off time	t _{OFF}		C _L = 35 pF, See Figure 18	Full	1.65 V to 1.95 V	2		12	ns
Due als h afana			0 05 -5	25°C	1.8 V	1	18	50	
Break-before- make time	t _{BBM}		C _L = 35 pF, See Figure 19	Full	1.65 V to 1.95 V	1		55	ns
Charge injection	Q _C	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C _L = 1 nF, See Figure 23	25°C	1.8 V		2		рС
NC, NO OFF capacitance	C _{NC(OFF)} , C _{NO(OFF)}	V_{NC} or $V_{NO} = V_{+}$ or GND, Switch OFF,	See Figure 17	25°C	1.8 V		18.5		pF
NC, NO ON capacitance	C _{NC(ON)} , C _{NO(ON)}	V_{NC} or $V_{NO} = V_{+}$ or GND, Switch ON,	See Figure 17	25°C	1.8 V		56.5		pF
COM ON capacitance	C _{COM(ON)}	$V_{COM} = V_+ \text{ or GND},$ Switch ON,	See Figure 17	25°C	1.8 V		56.5		pF
Digital input capacitance	CI	$V_{l} = V_{+}$ or GND,	See Figure 17	25°C	1.8 V		2		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON,	See Figure 20	25°C	1.8 V		105		MHz
OFF isolation	O _{ISO}	$ \begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array} $	Switch OFF, See Figure 21	25°C	1.8 V		-64		dB
Crosstalk	X _{TALK}	$\begin{array}{l} R_{L} = 50 \ \Omega, \\ f = 1 \ MHz, \end{array}$	Switch ON, See Figure 22	25°C	1.8 V		-64		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	1.8 V		0.06		%
Supply		-							
Positive supply	1	V = V or CND	Switch ON or OFF	25°C	1.95 V		10	25	nA
current	I+	$V_{I} = V_{+} \text{ or GND},$	Switch ON OFF	Full	1.90 V			50	ПA

(1) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

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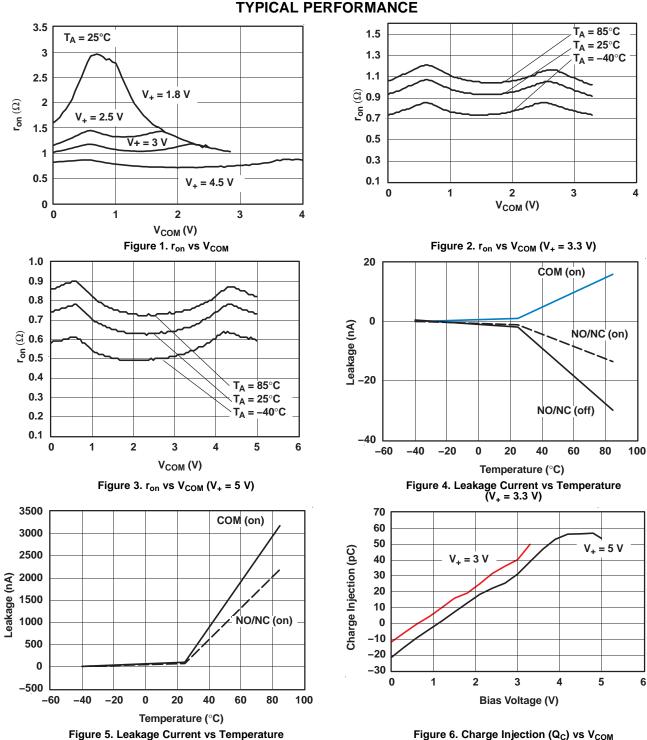


Figure 6. Charge Injection (Q_C) vs V_{COM}

 $(V_{+} = 5 V)$

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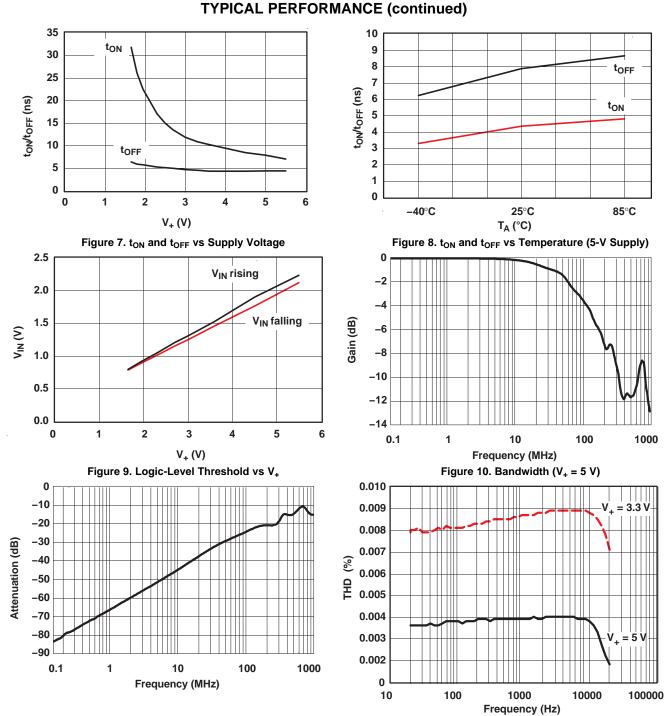


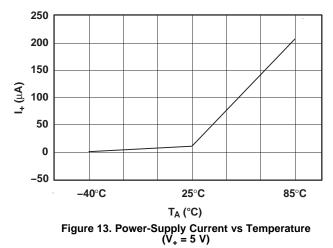
Figure 11. OFF Isolation vs Frequency

Figure 12. Total Harmonic Distortion vs Frequency

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TYPICAL PERFORMANCE (continued)



PIN DESCRIPTION							
PIN NO.	NAME	DESCRIPTION					
1	IN1	Digital control to connect COM to NO or NC					
2	NO1	Normally open					
3	GND	Digital ground					
4	NO2	Normally open					
5	IN2	Digital control to connect COM to NO or NC					
6	COM2	Common					
7	NC2	Normally closed					
8	V ₊	Power supply					
9	NC1	Normally closed					
10	COM1	Power supply					



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PARAMETER DESCRIPTION

SYMBOL	DESCRIPTION
V _{COM}	Voltage at COM
V _{NC}	Voltage at NC
V _{NO}	Voltage at NO
r _{on}	Resistance between COM and NC or COM and NO ports when the channel is ON
r _{peak}	Peak on-state resistance over a specified voltage range
∆r _{on}	Difference of r _{on} between channels in a specific device
r _{on(flat)}	Difference between the maximum and minimum value of ron in a channel over the specified range of conditions
I _{NC(OFF)}	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state under worst-case input and output conditions
I _{NC(PWROFF)}	Leakage current measured at the NC port during the power-down condition, $V_{+} = 0$
I _{NO(OFF)}	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state under worst-case input and output conditions
I _{NO(PWROFF)}	Leakage current measured at the NO port during the power-down condition, $V_{+} = 0$
I _{NC(ON)}	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) open
I _{NO(ON)}	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) open
I _{COM(ON)}	Leakage current measured at the COM port, with the corresponding channel (COM to NO or COM to NC) in the ON state and the output (NC or NO) open
I _{COM(PWROFF)}	Leakage current measured at the COM port during the power-down condition, $V_{+} = 0$
VIH	Minimum input voltage for logic high for the control input (IN)
V _{IL}	Maximum input voltage for logic low for the control input (IN)
VI	Voltage at the control input (IN)
I _{IH} , I _{IL}	Leakage current measured at the control input (IN)
t _{ON}	Turn-on time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning ON.
t _{OFF}	Turn-off time for the switch. This parameter is measured under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM, NC, or NO) signal when the switch is turning OFF.
t _{BBM}	Break-before-make time. This parameter is measured under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state.
Q _C	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NO or COM) output. This is measured in coulomb (C) and measured by the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_{COM}$. CL is the load capacitance and ΔV_{COM} is the change in analog output voltage.
C _{NC(OFF)}	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
C _{NO(OFF)}	Capacitance at the NO port when the corresponding channel (NO to COM) is OFF
C _{NC(ON)}	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
C _{NO(ON)}	Capacitance at the NO port when the corresponding channel (NO to COM) is ON
C _{COM(ON)}	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is ON
CI	Capacitance of control input (IN)
O _{ISO}	OFF isolation of the switch is a measurement of OFF-state switch impedance. This is measured in dB in a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state.
X _{TALK}	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This is measured in a specific frequency and in dB.
BW	Bandwidth of the switch. This is the frequency in which the gain of an ON channel is -3 dB below the DC gain.
THD	Total harmonic distortion is defined as the ratio of the root mean square (RMS) value of the second, third, and higher harmonics to the magnitude of fundamental harmonic.
I+	Static power-supply current with the control (IN) pin at V ₊ or GND



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PARAMETER MEASUREMENT INFORMATION

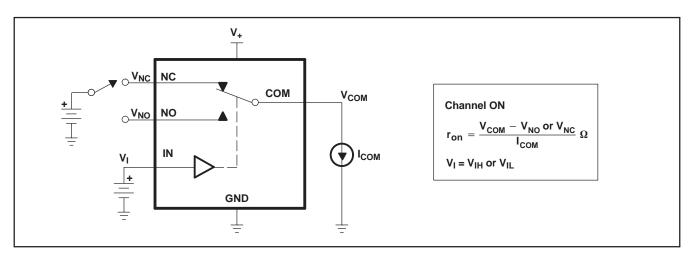


Figure 14. ON-State Resistance (ron)

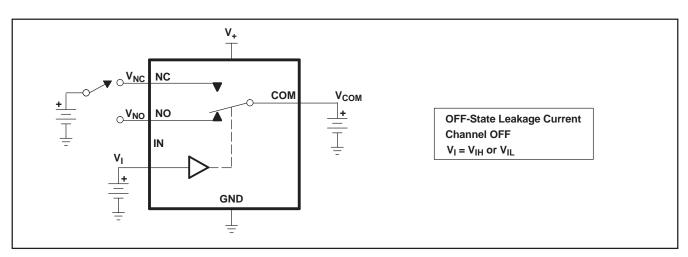
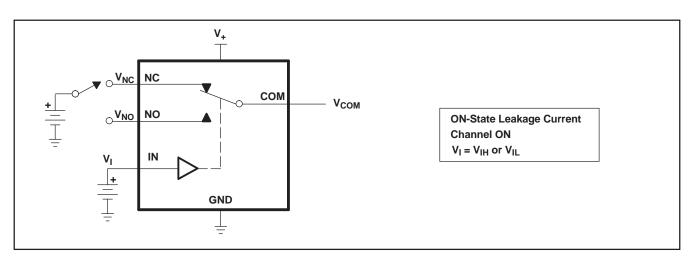


Figure 15. OFF-State Leakage Current (I_{NC(OFF)}, I_{NC(PWROFF)}, I_{NO(OFF)}, I_{NO(PWROFF)}, I_{COM(PWROFF)})







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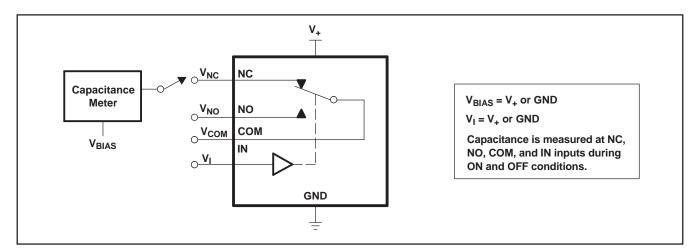
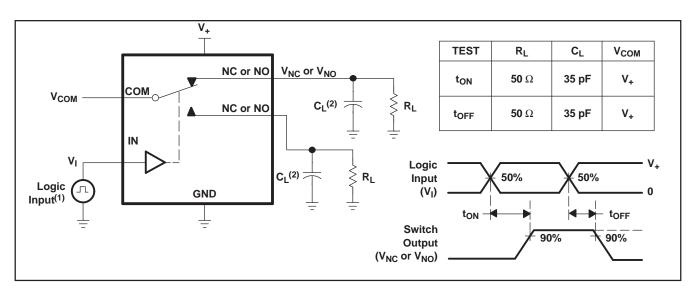


Figure 17. Capacitance (C₁, C_{COM(ON)}, C_{NC(OFF)}, C_{NO(OFF)}, C_{NC(ON)}, C_{NO(ON)})

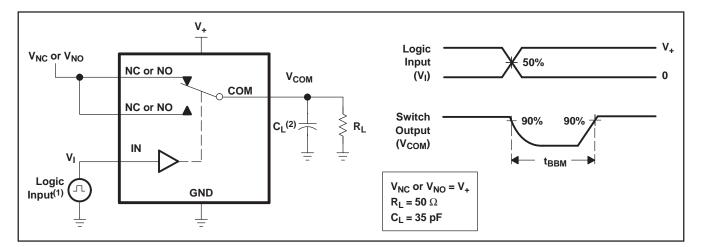


⁽¹⁾ All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f < 5 ns. t_f < 5 ns. ⁽²⁾ C_L includes probe and jig capacitance.

Figure 18. Turn-On (toN) and Turn-Off Time (toFF)



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⁽¹⁾ All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f < 5 ns. t_f < 5 ns. ⁽²⁾ C_L includes probe and jig capacitance.

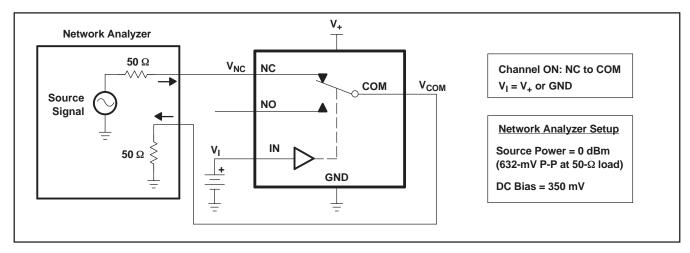


Figure 19. Break-Before-Make Time (t_{BBM})

Figure 20. Bandwidth (BW)



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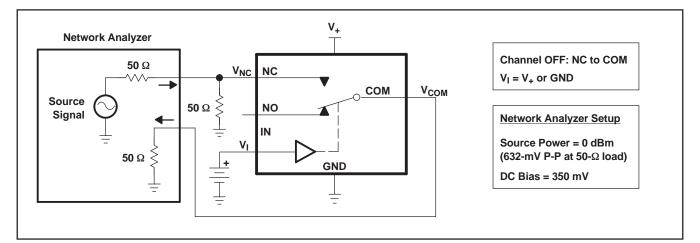


Figure 21. OFF Isolation (O_{ISO})

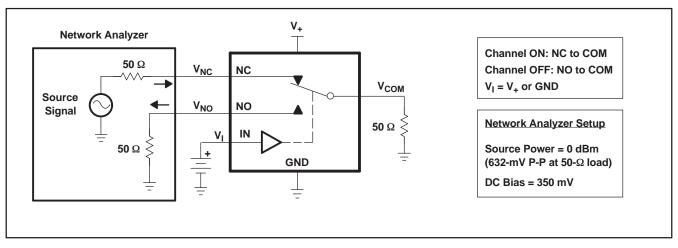
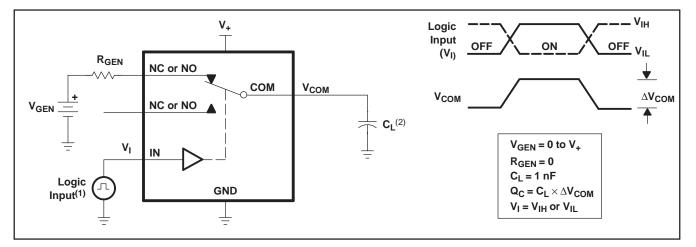


Figure 22. Crosstalk (X_{TALK})

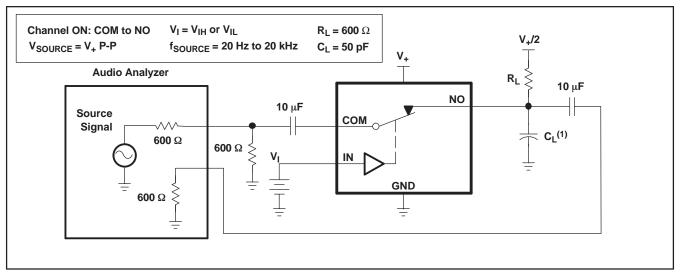


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⁽¹⁾ All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r < 5 ns, t_f < 5 ns. ⁽²⁾ C_L includes probe and jig capacitance.





 $^{(1)}$ C_L includes probe and jig capacitance.

Figure 24. Total Harmonic Distortion (THD)

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TS5A23159DGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A23159DGSRE4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A23159DGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A23159DGST	ACTIVE	MSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A23159DGSTE4	ACTIVE	MSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A23159DGSTG4	ACTIVE	MSOP	DGS	10	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A23159RSER	ACTIVE	QFN	RSE	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS5A23159RSERG4	ACTIVE	QFN	RSE	10	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

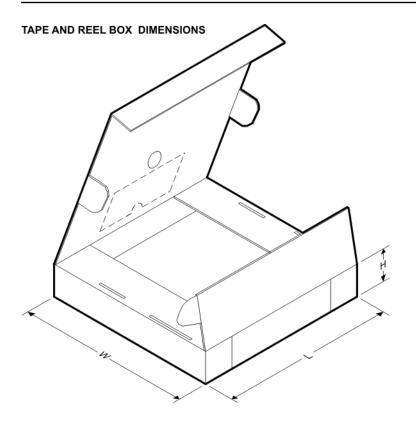


*A	*All dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	TS5A23159DGSR	MSOP	DGS	10	2500	330.0	13.0	5.3	3.4	1.4	8.0	12.0	Q1
	TS5A23159RSER	QFN	RSE	10	3000	179.0	8.4	1.75	2.25	0.65	4.0	8.0	Q1
	TS5A23159RSER	QFN	RSE	10	3000	180.0	9.2	1.68	2.13	0.76	4.0	8.0	Q1



PACKAGE MATERIALS INFORMATION

6-Nov-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A23159DGSR	MSOP	DGS	10	2500	358.0	335.0	35.0
TS5A23159RSER	QFN	RSE	10	3000	220.0	205.0	50.0
TS5A23159RSER	QFN	RSE	10	3000	202.0	201.0	28.0

DGS (S-PDSO-G10)

PLASTIC SMALL-OUTLINE PACKAGE

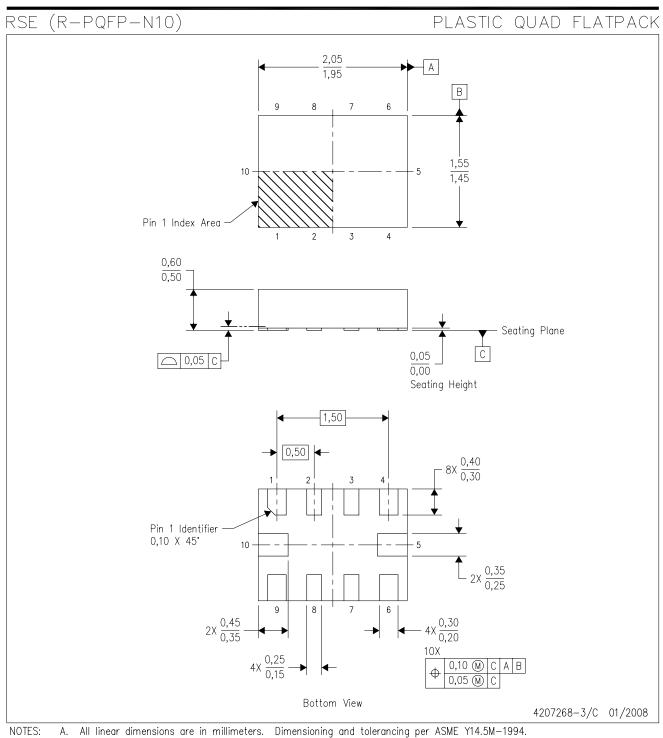


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation BA.



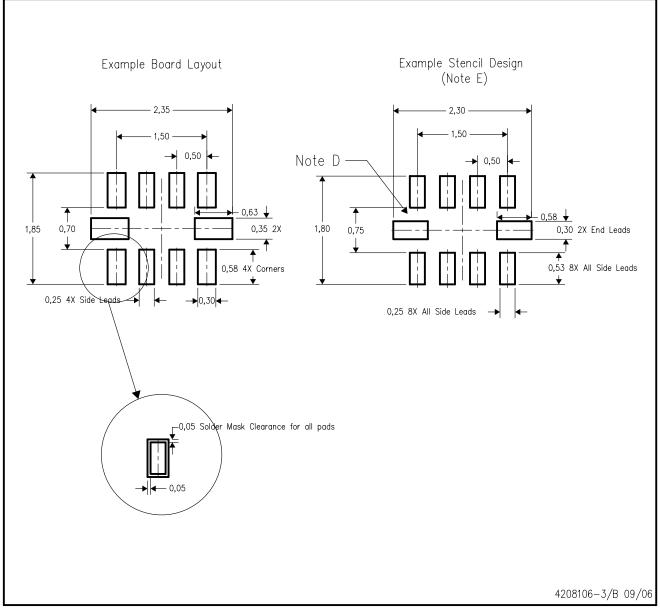
MECHANICAL DATA



B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No-Lead) package configuration.
D. This package complies to JEDEC MO-288 variation UEFD.



RSE (R-PQFP-N10)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
- E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
- F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- G. Side aperture dimensions over-print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.



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